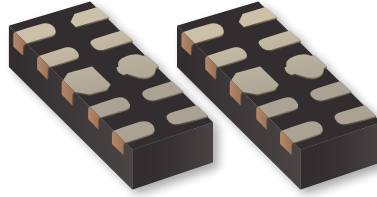




PRODUCT CHANGE NOTIFICATION

DIODES



Select Bourns® Surface Mount TVS Diode Arrays

Additional Supplier for Solder and/or Lead Frame Material

Riverside, California – July 2, 2024 – To accommodate increasing production demand and in the spirit of continuous improvement, effective January 1, 2025, Bourns will establish an additional existing wafer source and additional assembly house for select Surface Mount TVS Diode Arrays. There will also be a solder material supplier change for the Model CDDFN10-3324P and CDDFN10-3324P-13. The new supplier has been qualified and is included in the Bourns Authorized Vendor List. A list of affected part numbers is included below.

Affected Part Numbers

[CDDFN10-3324P](#)

CDDFN10-3324P-13

[CDDFN10-0524P](#)

Adding an assembly house will allow for the expansion of manufacturing capacity and the change to the sole solder supplier. The additional wafer source will help with the expansion of manufacturing capabilities.

The fit, form, function, quality, reliability and electrical performance of the affected products remain the same. Traceability will be maintained through lot code and date code.

Samples are available upon request. Bourns recommends that customers test the affected part numbers in their specific applications for verification of satisfactory performance.

Implementation dates are as follows:

Date that deliveries of products produced utilizing the above changes and products manufactured from both wafer sources will begin:

January 1, 2025

First date code using the above changes: **2501**

If you have any questions or need additional information, please feel free to [contact Customer Service/Inside Sales](#).

Users should verify that the described changes will not impact the performance of the product in their specific applications.

ESD2415